

News Release

FOR IMMEDIATE RELEASE

BTU Introduces Advanced Formic Acid Reflow Capability for Fluxless Semiconductor Packaging

WESTFORD, Mass., August 27, 2026 –BTU International, a leading supplier of advanced thermal processing equipment for the electronics manufacturing and semiconductor industries, today announced the availability of an advanced Formic Acid Reflow capability across multiple reflow oven platforms. Designed to support the increasing demands of advanced semiconductor packaging, power devices, and high-reliability electronic assemblies, the new process option enables fluxless soldering while delivering exceptional process control, lower operating costs, and superior solder joint quality.

As semiconductor packages continue to shrink while increasing in complexity, manufacturers require reflow processes capable of minimizing oxidation, reducing contamination, and improving long-term reliability. BTU's new Formic Acid Reflow

capability achieves ultra-low oxygen levels within the reflow chamber – reaching single-digit parts per million (ppm) – to provide an exceptionally clean processing environment that promotes superior solder wetting and consistent, repeatable results.

Unlike conventional systems that expose the entire thermal process to formic acid, BTU utilizes concentrated, targeted formic process zones, delivering the chemistry precisely where oxide reduction is required. This focused approach significantly reduces overall formic acid consumption while maintaining effective oxide removal, lowering operating costs and improving environmental efficiency without compromising process performance.

A key advantage of BTU's solution is its availability across multiple reflow platforms, allowing customers to select the system best suited for their application. The capability is fully compatible with BTU's industry-leading TrueFlat® technology, enabling manufacturers of ultra-thin substrates, advanced IC packages, and AI devices to combine fluxless processing with proven



substrate warpage control. By maintaining exceptional thermal uniformity and minimizing mechanical distortion throughout the reflow process, TrueFlat technology helps maximize yields for today's increasingly thin and fragile package designs.

“The transition toward finer interconnects, thinner substrates, and higher reliability requirements is driving increased adoption of fluxless reflow technologies,” said Rob DiMatteo General Manager of BTU International. “By combining ultra-low oxygen processing, highly efficient formic acid utilization, and compatibility with our TrueFlat and other industry-leading reflow platforms, BTU is delivering a solution that helps customers improve process performance while reducing operating costs.”

BTU's Formic Acid Reflow capability is well suited for a broad range of semiconductor manufacturing applications, including advanced packaging, flip chip, power devices, wafer-level packaging, and other high-reliability soldering processes where minimizing oxidation and residue is critical. The combination of precise atmosphere control, targeted formic acid delivery, and BTU's industry-recognized thermal process expertise provides manufacturers with a robust, production-ready solution for next-generation semiconductor assembly.

More information about BTU International is available at www.btu.com.

About BTU International

BTU International, a wholly-owned subsidiary of Amtech Group (Nasdaq: ASYS), is a global supplier and technology leader of advanced thermal processing equipment in the electronics manufacturing market. BTU's high-performance reflow ovens are used in the production of SMT printed circuit board assemblies and in semiconductor packaging processes. BTU also specializes in precision controlled, high-temperature belt furnaces for a wide range of custom applications, such as brazing, direct bond copper (DBC), diffusion, and sintering. BTU has operations in Westford, Massachusetts, and Shanghai, China, with direct sales and service in the U.S.A., Asia and Europe. Information about BTU International is available at www.btu.com.

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